

NCE P-Channel Enhancement Mode Power MOSFET

Description

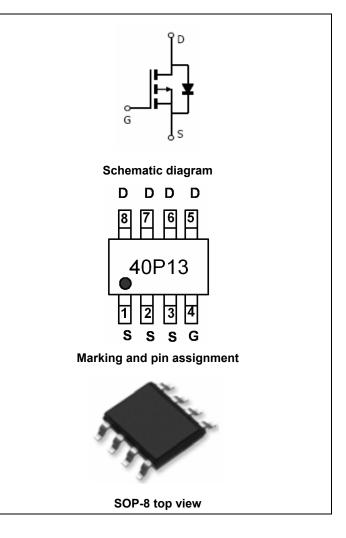
The NCE40P13S uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

- V_{DS} =-40V, I_{D} =-13A $R_{DS(ON)}$ <12m Ω @ V_{GS} =-10V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

Application

- Power switching application
- Hard switched and high frequency circuits
- DC-DC converter



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
40P13	NCE40P13S	SOP-8	Ø330mm	12mm	2500 units

Absolute Maximum Ratings (T_A=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	-40	V	
Gate-Source Voltage	V _{GS}	±20	V	
Drain Current-Continuous	I _D	-13	Α	
Drain Current-Continuous(T _C =100℃)	I _D (100℃)	-9	Α	
Pulsed Drain Current	I _{DM}	50	Α	
Maximum Power Dissipation	P _D	2.5	W	
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	$^{\circ}$	

Thermal Characteristic

Thermal Resistance ,Junction-to-Ambient(Note 2)	$R_{\theta JA}$	50	°C/W
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Electrical Characteristics (T_A=25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-40	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-40V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =-250μA	-1.3	-2	-2.5	V
Drain-Source On-State Resistance	R _{DS(ON)}	V_{GS} =-10 V , I_D =-12 A	-	9	12	mΩ
Forward Transconductance	g FS	V _{DS} =-15V,I _D =-10A	35	-	-	S
Dynamic Characteristics (Note4)			•			
Input Capacitance	C _{lss}	V = 20V/V =0V	-	2800	-	PF
Output Capacitance	Coss	V_{DS} =-20V, V_{GS} =0V, F=1.0MHz	-	320	-	PF
Reverse Transfer Capacitance	C _{rss}	r-1.0ivinz	-	220	-	PF
Switching Characteristics (Note 4)			•			
Turn-on Delay Time	t _{d(on)}		-	11	-	nS
Turn-on Rise Time	t _r	V_{DD} =-20 V , P_{L} =2 Ω	-	75	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-10 V , R_{GEN} =6 Ω	-	89	-	nS
Turn-Off Fall Time	t _f		-	35	-	nS
Total Gate Charge	Qg	V = 20V/I = 42A	-	40	-	nC
Gate-Source Charge	Q_{gs}	V_{DS} =-20V, I_{D} =-12A, V_{GS} =-10V	-	6	-	nC
Gate-Drain Charge	Q_{gd}	v _{GS} 10 v	-	12	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-6A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	-13	Α

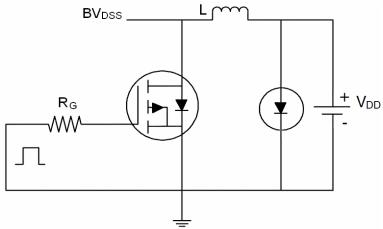
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- **3.** Pulse Test: Pulse Width ≤ 300μ s, Duty Cycle ≤ 2%.
- **4.** Guaranteed by design, not subject to production

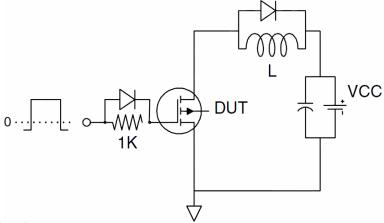


Test Circuit

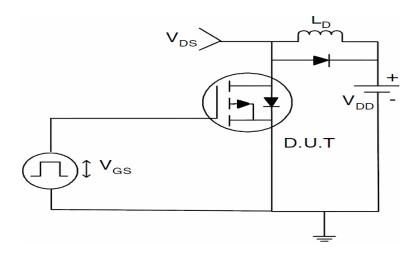
1) E_{AS} Test Circuit



2) Gate Charge Test Circuit



3) Switch Time Test Circuit



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Typical Electrical and Thermal Characteristics (Curves)

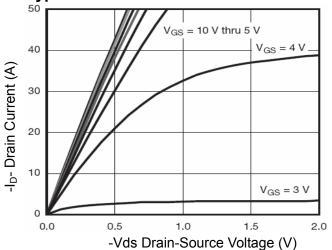


Figure 1 Output Characteristics

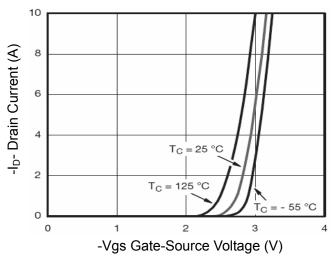


Figure 2 Transfer Characteristics

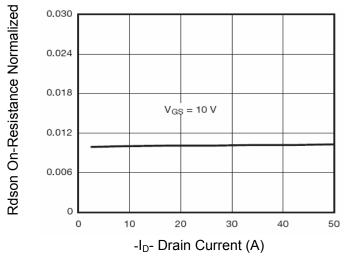


Figure 3 Rdson- Drain Current

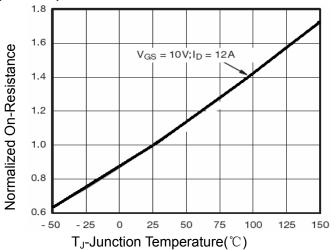


Figure 4 Rdson-Junction Temperature

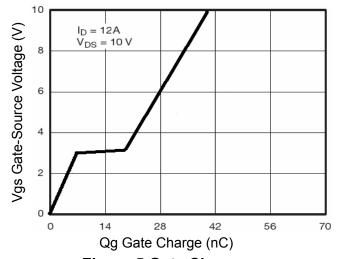


Figure 5 Gate Charge

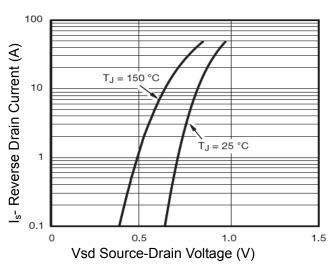


Figure 6 Source- Drain Diode Forward

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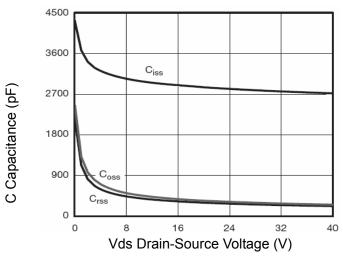


Figure 7 Capacitance vs Vds

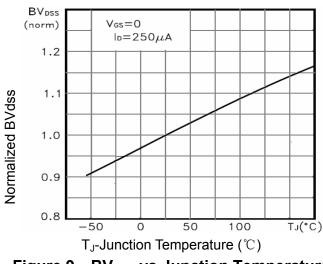


Figure 9 BV_{DSS} vs Junction Temperature

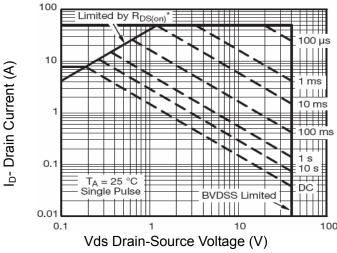


Figure 8 Safe Operation Area

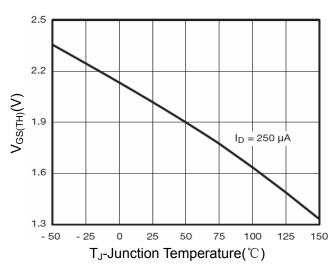


Figure 10 V_{GS(th)} vs Junction Temperature

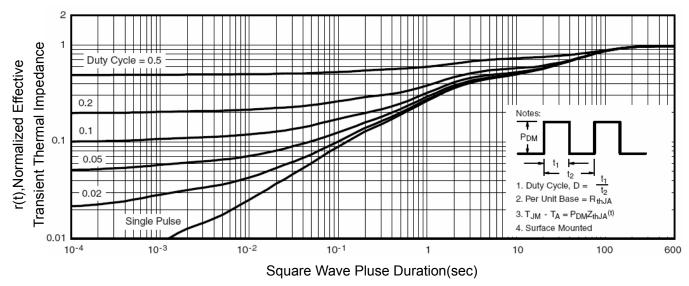
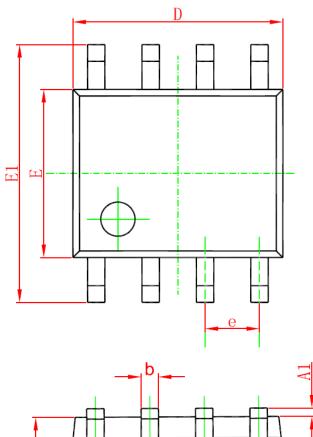


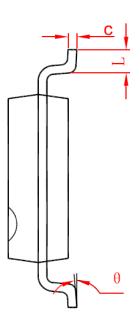
Figure 11 Normalized Maximum Transient Thermal Impedance

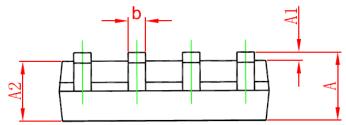
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SOP-8 Package Information







Ch a l	Dimensions Ir	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
A	1. 350	1. 750	0. 053	0. 069	
A1	0. 100	0. 250	0.004	0. 010	
A2	1. 350	1. 550	0.053	0. 061	
b	0. 330	0. 510	0. 013	0. 020	
С	0. 170	0. 250	0.006	0. 010	
D	4. 700	5. 100	0. 185	0. 200	
Е	3. 800	4. 000	0. 150	0. 157	
E1	5. 800	6. 200	0. 228	0. 244	
е	1. 270 (BSC)		0. 050 (BSC)		
L	0. 400	1. 270	0. 016	0. 050	
θ	0°	8°	0°	8°	

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